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UTILITY
PATENT APPLICATION
TRANSMITTAL

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Attorney Docket
No.
93-0421.03

Total
Pages

First Named Inventor or Application Identifier

Trung T. Doan

Express Mail Label No.

EL002998669US

APPLICATION ELEMENTS

See MPEP chapter 600 concerning utility patent application contents.

ADDRESS TO:

Assistant Commissioner for Patents
Box Patent Application
Washington, DC 20231

1. ☒ Fee Transmittal Form
(Submit an original, and a duplicate for fee processing)
2. ☒ Specification Total Pages 8
(preferred arrangement set forth below)
 - Descriptive
 - Cross References to Related Application
 - Statement Regarding Fed sponsored R & D
 - Reference to Microfiche Appendix
 - Background of the Invention
 - Brief Summary of the Invention
 - Brief Description of the Drawings (if filed)
 - Detailed Description
 - Claim(s)
 - Abstract of the Disclosure
3. ☒ Drawing(s) (35 USC 113) Total Sheets 2
Total Pages 6
4. Oath or Declaration
 - a. ☐ Newly executed (original or copy)
 - b. ☒ Copy from a prior application (37CFR 1.63(d)) (for continuation/divisional with Box 17 completed)(Note Box 5 below)
 - i. ☐ DELETION OF INVENTOR(S)
Signed statement attached deleting inventor(s) named in the prior application, see 37 CFR 1.63(d)(2) and 1.33(b).
5. ☐ Incorporation By Reference (useable if Box 4b is checked)
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.

6. ☐ Microfiche Computer Program (Appendix)
7. Nucleotide and/or Amino Acid Sequence Submission
(if applicable, all necessary)
 - a.
 - b. ☐ Computer Readable Copy
 - c. ☐ Paper Copy (identical to computer copy)
☐ Statement verifying identity of above copies

ACCOMPANYING APPLICATION PARTS

8. ☐ Assignment Papers (cover sheet & document(s))
9. ☒ 37 CFR 3.73(b) Statement ☒ Power of Attorney
(where there is an assignee)
10. ☐ English Translation Document (if applicable)
11. ☐ Information Disclosure Statement (IDS)/PTO-1449 ☐ Copies of IDS Citations
12. ☒ Preliminary Amendment
13. ☒ Return Receipt Postcard (MPEP 503)
14. ☐ Small Entity ☐ Statement filed in prior application
Statement(s) Status still proper and desired
15. ☐ Certified Copy of Priority Document(s)
(if foreign priority is claimed)
16. ☐ Other

17. ☒ Continuation ☐ Divisional ☐ Continuation-in-part (CIP) of prior application No: _____

18. CORRESPONDENCE ADDRESS

- ☐ Customer Number or Bar Code Label ☐ Correspondence address below
(Insert Customer No. or Attach bar code label here)

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FEE TRANSMITTAL**Complete if Known**

FEE TRANSMITTAL		Application Number	
		Filing Date 8/14/98	
		First Named Inventor Trung T. Doan	
		Group Art Unit	
		Examiner Name	
TOTAL AMOUNT OF PAYMENT	(\$) 1814	Attorney Docket Number	93-0421.03

METHOD OF PAYMENT (check one)

1. ☒ The Commissioner is hereby authorized to charge indicated fees and credit any over payments to:

Deposit Account Number: 13-3092, Order No. 93-0421.03

Deposit Account Name: Micron Technology, Inc.

- ☒ Charge Any Additional Fee Required Under 37 CFR 1.16 and 1.17 ☐ Charge the Issue Fee Set in 37 CFR 1.18 at the Mailing of the Notice of Allowance, 37 CFR 1.31(b)

2. ☐ Payment Enclosed:

☐ Check ☐ Money Order ☐ Other

FEE CALCULATION (fees effective 10/01/96)**1. FILING FEE**

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
101	790	201	395	Utility filing fee	790
106	330	206	165	Design filing fee	
107	540	207	270	Plant filing fee	
108	790	208	395	Reissue filing fee	
114	150	214	75	Provisional filing fee	
SUBTOTAL (1)					(\$) 790

2. CLAIMS

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
103	22	203	11	Claims in excess of 20	
102	82	202	41	Independent claims in excess of 3	
104	270	204	135	Multiple dependent claim	
109	82	209	41	Reissue independent claims over original patent	
110	22	210	11	Reissue claims in excess of 20 and over original patent	
SUBTOTAL (2)					(\$) 1024

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Fee Code	Entity Fee (\$)	Small Fee Code	Entity Fee (\$)	Fee Description	Fee Paid
105	130	205	65	Surcharge - late filing fee or oath	
127	50	227	25	Surcharge - late provisional filing or cover sheet.	
139	130	139	130	Non-English specification	
147	2,520	147	2,520	For filing a request for reexamination	
112	920	112	920	Requesting publication of SIR prior to Examiner action	
113	1,840	113	1,840	Requesting publication of SIR after Examiner action	
115	110	215	55	Extension for response within first month	
116	400	216	200	Extension for response within second month	
117	950	217	475	Extension for response within third month	
118	1,570	218	755	Extension for response within fourth month	
119	310	219	155	Notice of Appeal	
120	310	220	155	Filing a brief in support of an appeal	
121	270	221	135	Request for oral hearing	
138	1,510	138	1,510	Petition to institute a public use proceeding	
140	110	240	55	Petition to revive unavoidably abandoned application	
141	1,320	241	660	Petition to revive unintentionally abandoned application	
142	1,320	242	660	Utility issue fee (or reissue)	
143	450	243	225	Design issue fee	
144	670	244	335	Plant issue fee	
122	130	122	130	Petitions to the Commissioner	
123	50	123	50	Petitions related to provisional applications	
126	240	126	240	Submission of Information Disclosure Stmt	
581	40	581	40	Recording each patent assignment per property (times number of properties)	
146	790	246	395	Filing a submission after final rejection (37 CFR 1.129(a))	
149	790	249	395	For each additional invention to be examined (37 CFR 1.129(b))	
Other fee (specify) _____					
Other fee (specify) _____					
SUBTOTAL (3)					(\$)
* Reduced by Basic Filing Fee Paid					

SUBMITTED BY

Typed or Printed Name	Charles B. Brantley II	Reg. Number	38,086	Complete (if applicable)	
Signature	<i>Charles Brantley</i>	Date	8/14/98	Deposit Acct. User ID	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Trung T. Doan

Serial No.:

Filed: August 14, 1998

Title: CHEMICAL DISPENSING SYSTEM FOR
SEMICONDUCTOR WAFER PROCESSING

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Group Art Unit:

Examiner:

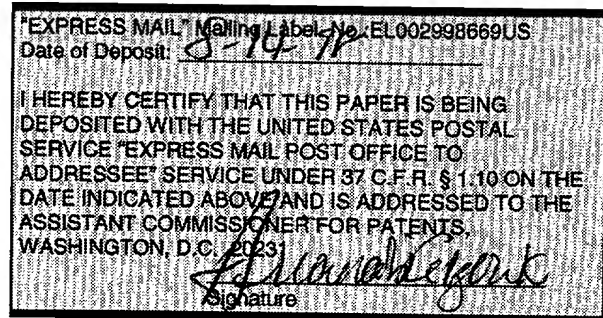
Atty. Docket: 93-0421.03

August 14, 1998

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents

Washington, D.C. 20231



Dear Sir:

The application filed herewith is a continuation of application serial # 08/944,135, which is a file wrapper continuation of application serial # 08/618,072. After awarding this application the priority filing date of the original application (serial # 08/618,072) filed February 27, 1996, please amend the current application as follows.

IN THE SPECIFICATION:

After the title, please include the following --

RELATED APPLICATIONS

This application is a continuation of U.S. Application Serial Number 08/944,135, which is a file wrapper continuation of U.S. Application Serial Number 08/618,072, filed February 27, 1996. --

IN THE CLAIMS:

Please cancel claims 2-11 without prejudice.

Please add the following claims:

12. A processor for a spin coating device including a chuck defining a wafer plane, comprising:
 - at least one dispenser; and
 - a suction mechanism generally around said at least one dispenser and offset from said wafer plane.
13. The processor in claim 12, wherein said at least one dispenser further comprises:
 - a first dispenser on a first side of said wafer plane; and
 - a second dispenser on a second side of said wafer plane.
14. A bead remover for a wafer having an edge, comprising:
 - a negative pressure mechanism configured to be spaced from said edge; and
 - a solvent-dispensing mechanism aligned with said negative pressure mechanism.

15. The bead remover of claim 14, wherein said solvent-dispensing mechanism is concentric to said negative pressure mechanism.

16. The bead remover of claim 15, wherein said solvent-dispensing mechanism is generally within said negative pressure mechanism.

17. An edge bead remover configured to service a spinning wafer, comprising:
a nozzle configured to apply a solvent to an edge of said wafer; and
a vacuum mechanism enveloping said nozzle and offset from a surface of said wafer.

18. The edge bead remover of claim 17, wherein said vacuum mechanism is configured to remove said solvent from said edge.

19. The edge bead remover of claim 18, wherein said vacuum mechanism envelopes said edge.

20. A material removal system for a wafer having an edge, comprising:
a negative pressure device defining a vacuum area intersecting said edge; and
a solvent dispenser intersecting said vacuum area.

21. The material removal system of claim 20, wherein said negative pressure device is distal from said edge.

22. An edge bead removal system for a wafer having an edge and a top and a bottom, comprising:
a first solvent nozzle poised above said top of said wafer at said edge;
a second solvent nozzle poised below said bottom of said wafer at said edge; and
a suction device encompassing said first solvent nozzle and said second solvent nozzle.

23. The edge bead removal system in claim 22, wherein said suction device encompasses said top and said bottom of said wafer at said edge.

24. A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from an edge of said workpiece; and

a first solvent dispenser within said negative pressure device and disposed toward said edge.

25. The chemical dispensing system in claim 24, wherein said portal is spaced around said edge.

26. The chemical dispensing system in claim 25, further comprising a second solvent dispenser within said negative pressure device, disposed toward said edge, and opposing said first solvent dispenser.

27. The chemical dispensing system in claim 26, wherein said first solvent dispenser and said second solvent dispenser are within said portal.

28. A chemical remover for a substrate edge, comprising:

a nozzle directed toward said substrate edge and configured to couple to a solvent source; and

a vacuum device spaced from said substrate edge and directed toward said nozzle.

29. A profiler for a wafer edge, comprising:

a solvent dispenser perpendicular to said wafer edge; and

a solvent vacuumer surrounding at least a portion of said solvent dispenser and separate from said wafer edge.

30. The profiler in claim 29, wherein said solvent dispenser further comprises a location wherein solvent exits said solvent dispenser; and wherein said solvent vacuummer surrounds said location.

31. The profiler in claim 30, further comprising an additional solvent dispenser perpendicular to said wafer edge; wherein said solvent vacuummer surrounds at least a portion of said additional solvent dispenser.

32. The profiler in claim 31, wherein said solvent dispenser is disposed toward a top side of said wafer edge.

33. The profiler in claim 32, wherein said additional solvent dispenser is disposed toward a bottom side of said wafer edge.

34. A device for an edge bead, comprising:
a dispenser configured to release a chemical toward said edge bead; and
a splash controller around said dispenser, physically unattached from said edge bead, and configured to draw said chemical toward said splash controller.

35. The device in claim 34, wherein said splash controller is configured to generate a gas pressure around said edge bead that is lower than an ambient gas pressure.

36. The device in claim 35, wherein said splash controller is configured to physically intercept said chemical.

37. The device in claim 36, wherein said splash controller is around said edge bead.

38. A removal system for a workpiece having an overlying material, comprising:
a nozzle having an extended position and a retracted position, wherein said nozzle

is disposed toward said workpiece and configured to dispense a chemical toward said workpiece while in said extended position; and
a suction applicator commensurately movable with said nozzle and defining a port around said nozzle, wherein said suction applicator is configured to withdraw said chemical and said material at a distance from said workpiece.

39. The removal system in claim 38, wherein said nozzle is further configured to dispense said chemical toward said material.

40. The removal system in claim 38, wherein said nozzle is further configured to dispense said chemical toward a portion of said workpiece interposed between said nozzle and said material.

41. A processor for a semiconductor wafer that is generally exposed to an ambient air pressure, comprising:

a splash control apparatus configured to define a lower air pressure area on more than one side of said workpiece; and
at least one chemical dispenser poised toward said workpiece.

42. The processor in claim 41, wherein said splash control apparatus further comprises a housing overaccommodating a dimension of said workpiece.

43. The processor in claim 42, wherein said splash control apparatus defines an opening wider than a width of said workpiece.

Please address further correspondence with this application to: Charles B.
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83706-9632, telephone number (208) 368-4557.

Charles Brantley 8/14/98
Charles B. Brantley II, Reg. No. 38,086

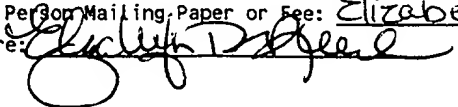
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Date of Deposit 2/27/96

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"Express Mail Post Office to Addressee" services under 37 C.F.R. 1.10 on the date indicated above and is addressed to the Assistant Commissioner For Patents, Washington, D.C. 20231.

Name of Person Mailing Paper or Fee: Elizabeth D. Reed

Signature: 

ATTORNEY
DOCKET NO. MICR157

**CHEMICAL DISPENSING SYSTEM FOR SEMICONDUCTOR
WAFER PROCESSING**

INVENTOR:

TRUNG T. DOAN

CHEMICAL DISPENSING SYSTEM FOR SEMICONDUCTOR WAFER PROCESSING

FIELD OF THE INVENTION

The invention relates generally to the manufacture of semiconductor devices. More particularly, the invention relates to a chemical dispensing system for semiconductor wafer processes such as removing the edge bead formed during spin coating processes.

BACKGROUND OF THE INVENTION

Coating materials such as photoresist are typically applied to a semiconductor wafer by flowing liquid coating material onto the top surface of the wafer while it is spinning. The wafer is held on a disk shaped, rotating spin chuck. The diameter of the chuck is slightly less than the diameter of the wafer. The chuck is positioned so that the wafer lies on the chuck in a level horizontal plane. In operation, the backside or inactive surface of the wafer is placed onto the chuck. The chuck applies a suction to the backside of the wafer to hold the wafer in place on the chuck. The chuck is rotated by a motor driven axle that extends down from the chuck. As the wafer is rotated on the chuck, liquid photoresist material is applied to the center of the wafer. The photoresist spreads radially outward from the center of the wafer towards the edge to coat the top of the wafer. Ideally, all excess coating material is ejected from the edge of the wafer. In practice, however, some excess photoresist tends to collect at and form a bead along the edge of the wafer.

A solvent is dispensed along the edge of the wafer to dissolve the edge bead and remove the resist from the extreme edge of the wafer. The solvent may be dispensed through a nozzle directed toward the backside edge of the wafer, in which case it curls up around to the top of the wafer to dissolve the edge bead, or the solvent may be dispensed directly onto the top edge of the wafer. In either

case, the process allows solvent and dissolved photoresist to be splashed about and often leaves a jagged edge profile on the photoresist or other coating material.

SUMMARY OF THE INVENTION

Accordingly, it is one object of the invention generally to increase the effectiveness of conventional edge bead removal systems. It is another object to control solvent and particle splashing during the process of removing the edge bead from the coating material. It is a further object of the invention to improve the edge profile of the coating material. These and other objects and advantages may be achieved in general by a method for dispensing a chemical, such as an edge bead removal solvent, onto a semiconductor wafer. The method comprises the steps of dispensing the chemical selectively onto the wafer and applying a suction to the area immediately surrounding the location at which the chemical is dispensed onto the wafer. Preferably, the suction is applied substantially simultaneously with the dispensing of the chemical.

One specific version of the invention provides an edge bead removal system wherein suction is applied to the area immediately surrounding the solvent dispensing nozzle to remove dissolved coating material and excess solvent from the wafer. In one aspect of this system, an apparatus for removing the edge bead includes a mechanism for dispensing a solvent selectively onto the edge of the wafer, and a mechanism surrounding the dispensing mechanism for vacuuming excess solvent and dissolved coating material from the edge of the wafer. The edge bead removal apparatus preferably also includes mechanisms for spinning the semiconductor wafer and coating material on the spinning wafer. Another aspect of the system provides a method for removing an edge bead of a coating of material that has been spun onto the surface of a semiconductor wafer. The method includes the steps of dispensing a solvent selectively onto the edge of the wafer to dissolve the coating material at the extreme edge of the wafer, and applying a suction to vacuum excess solvent and dissolved coating material from

the wafer. Preferably, the suction is applied to the area immediately surrounding the location at which the solvent is dispensed onto the wafer simultaneously with the dispensing of the solvent.

DESCRIPTION OF THE DRAWINGS

5 Fig. 1 is a partial side view of a spin coating device having the surrounding suction of the present invention wherein the edge bead removal solvent is dispensed onto the top of the wafer.

Fig. 2 is a partial side view of a spin coating device having the surrounding suction of the present invention wherein the edge bead removal solvent is
10 dispensed onto both the top and bottom of the wafer.

DETAILED DESCRIPTION OF THE INVENTION

Referring to Fig. 1, wafer 10 is positioned on spin chuck 12. Spin chuck 12 is mounted on axle 14. Axle 14 is operatively coupled to a drive mechanism, such as an electric motor (not shown). The diameter of spin chuck 12 is less than the
15 diameter of wafer 10 so that wafer 10 extends beyond the edge of spin chuck 12. a first nozzle 15 for dispensing coating material onto wafer 10 is positioned above and, typically, at the center of wafer 10. A second nozzle 16 for dispensing solvent to dissolve the edge bead is disposed above the edge of wafer 10. Solvent dispensing nozzle 16 is surrounded by vacuum port 18. Vacuum port 18 is
20 operatively coupled to a source of negative pressure, such as a vacuum pump (not shown).

In operation, a suction is applied to the wafer 10 to hold it in place on spin chuck 12. Spin chuck 12 is rotated to spin wafer 10 as a solution of coating material, such as photoresist, is applied through first nozzle 15. Although
25 photoresist is used herein as one illustrative coating, the invention is applicable to any soluble coating. The coating material is distributed across the top surface of wafer 10 largely due to centrifugal forces created by the spinning wafer. Excess

coating material tends to collect at and form a bead along the edge 22 of wafer 10. To remove the edge bead, a solvent is sprayed through nozzle 16 onto the edge 22 of wafer 10 to dissolve the coating material at the extreme edge of the wafer. At the same time, the dissolved coating material and excess solvent is suctioned away from wafer 10 through vacuum port 18. Preferably, vacuum port 18 surrounds nozzle 16 and a suction is thereby applied to the area immediately surrounding nozzle 16, as shown in Fig. 1. Also, vacuum port 18 preferably moves with nozzle 16 as it is extended and retracted into position over wafer 10. This "surround vacuum" controls solvent and particle splashing during the process of removing the edge bead from the coating material. In addition, it is believed the surround vacuum improves the edge profile of the coating material.

Fig. 2 illustrates a second embodiment of the invention wherein the solvent is applied to both the top and bottom surfaces of wafer 10. Wafer 10 is positioned on spin chuck 12 which is rotated on axle 14. An edge bead removal solvent is supplied through tubes 20 to dispensing nozzles 16. The solvent is sprayed through nozzles 16 onto the edge 22 of wafer 10 and, at the same time, the dissolved coating material and excess solvent is suctioned away through vacuum ports 18.

Conventional spin coating machines, such as a SVG Coat Track or TEL Mark 8, can be adapted for use in accordance with the invention as described herein. With the exception of the vacuum ports, the above described components are conventional and well known to those skilled in the art. There has been shown and described an edge bead removal system wherein a suction is applied to the area surrounding the solvent dispensing nozzle to control splashing and improve the edge profile of the coating material. The particular embodiments shown and described herein are for purposes of example and should not be construed to limit the invention as set forth in the appended claims.

CLAIMS

What is claimed is:

- 1 1. An apparatus for removing an edge bead of a coating of material that has
2 been spun onto the surface of a semiconductor wafer, the apparatus comprising:
3 a. means for dispensing a solvent selectively onto the edge of the wafer;
4 and
5 b. means surrounding the dispensing means for vacuuming excess
6 solvent and dissolved coating material from the edge of the wafer.
- 1 2. An apparatus according to Claim 1, wherein the dispensing means is a
2 nozzle and the vacuuming means comprises a vacuum port surrounding the nozzle.
- 1 3. An apparatus according to Claim 1, further comprising:
2 a. means for spinning the semiconductor wafer; and
3 b. means for applying a coating material to the spinning wafer.
- 1 4. A method for removing an edge bead of a coating of material that has been
2 spun onto the surface of a semiconductor wafer, the method comprising the steps
3 of:
4 a. dispensing a solvent selectively onto the edge of the wafer to dissolve
5 the coating material at the extreme edge of the wafer; and
6 b. applying a suction to vacuum excess solvent and dissolved coating
7 material from the edge of the wafer.
- 1 5. A method according to Claim 4, wherein the suction is applied to an area
2 immediately surrounding a location at which the solvent is dispensed onto the
3 wafer.

1 6. A method according to Claim 4, wherein the step of vacuuming is performed
2 substantially simultaneously with the step of dispensing.

1 7. A method for spin coating a semiconductor wafer with a soluble material,
2 comprising the steps of:
3 a. spinning the semiconductor wafer;
4 b. applying a coating material to the spinning wafer;
5 c. dispensing a solvent selectively onto the edge of the wafer to dissolve
6 the coating material at the extreme edge of the wafer; and
7 d. applying a suction to the edge of the wafer to vacuum excess solvent
8 and dissolved coating material from the edge of the wafer.

1 8. A method according to Claim 7, wherein the suction is applied to an area
2 immediately surrounding a location at which the solvent is dispensed onto the
3 wafer.

1 9. A method according to Claim 7, wherein the step of dispensing the solvent
2 is performed substantially simultaneously with the step of applying a suction.

1 10. A method for dispensing a chemical onto a semiconductor wafer, comprising
2 the steps of:
3 a. dispensing the chemical selectively onto the wafer; and
4 b. applying a suction to an area immediately surrounding a location at
5 which the chemical is dispensed onto the wafer.

1 11. A method according to Claim 10, wherein the suction is applied substantially
2 simultaneously with the dispensing of the chemical.

ABSTRACT

A method for dispensing a chemical, such as an edge bead removal solvent, onto a semiconductor wafer comprising the steps of dispensing the chemical selectively onto the wafer and applying a suction to the area immediately surrounding the location at which the chemical is dispensed onto the wafer.

- 5 Preferably, the suction is applied substantially simultaneously with the dispensing of the chemical. One specific version of the invention provides an edge bead removal system wherein suction is applied to the area immediately surrounding the solvent dispensing nozzle to remove dissolved coating material and excess solvent from the wafer. In one aspect of this system, an apparatus for removing the edge
- 10 bead includes a mechanism for dispensing a solvent selectively onto the edge of the wafer, and a mechanism surrounding the dispensing mechanism for vacuuming excess solvent and dissolved coating material from the edge of the wafer. The edge bead removal apparatus preferably also includes mechanisms for spinning the semiconductor wafer and coating material on the spinning wafer. Another aspect
- 15 of the system provides a method for removing an edge bead of a coating of material that has been spun onto the surface of a semiconductor wafer. The method includes the steps of dispensing a solvent selectively onto the edge of the wafer to dissolve the coating material at the extreme edge of the wafer, and applying a suction to vacuum excess solvent and dissolved coating material from
- 20 the wafer.

FIG. 1 is a perspective view of a device 10 for measuring the thickness of a material 12.

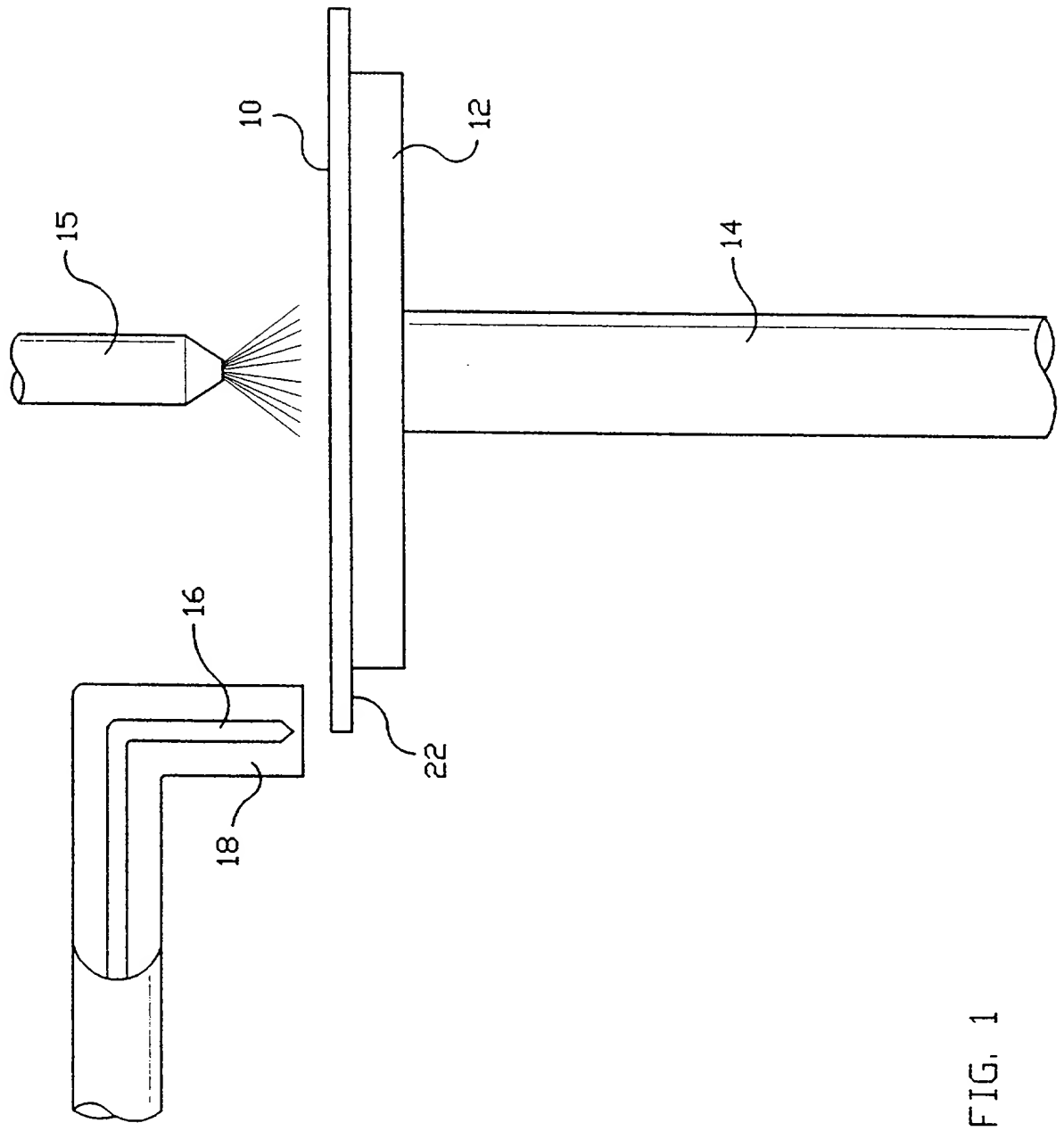


FIG. 1

	1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100	2101	2102	2103	2104	2105	2106	2107	2108	2109	2110	2111	2112	2113	2114	2115	2116	2117	2118	2119	2120	2121	2122	2123	2124	2125	2126	2127	2128	2129	2130	2131	2132	2133	2134	2135	2136	2137	2138	2139	2140	2141	2142	2143	2144	2145	2146	2147	2148	2149	2150	2151	2152	2153	2154	2155	2156	2157	2158	2159	2160	2161	2162	2163	2164	2165	2166	2167	2168	2169	2170	2171	2172	2173	2174	2175	2176	2177	2178	2179	2180	2181	2182	2183	2184	2185	2186	2187	2188	2189	2190	2191	2192	2193	2194	2195	2196	2197	2198	2199	2200	2201	2202	2203	2204	2205	2206	2207	2208	2209	2210	2211	2212	2213	2214	2215	2216	2217	2218	2219	2220	2221	2222	2223	2224	2225	2226	2227	2228	2229	2230	2231	2232	2233	2234	2235	2236	2237	2238	2239	2240	2241	2242	2243	2244	2245	2246	2247	2248	2249	2250	2251	2252	2253	2254	2255	2256	2257	2258	2259	2260	2261	2262	2263	2264	2265	2266	2267	2268	2269	2270	2271	2272	2273	2274	2275	2276	2277	2278	2279	2280	2281	2282	2283	2284	2285	2286	2287	2288	2289	2290	2291	2292	2293	2294	2295	2296	2297	2298	2299	2300	2301	2302	2303	2304	2305	2306	2307	2308	2309	2310	2311	2312	2313	2314	2315	2316	2317	2318	2319	2320	2321	2322	2323	2324	2325	2326	2327	2328	2329	2330	2331	2332	2333	2334	2335	2336	2337	2338	2339	2340	2341	2342	2343	2344	2345	2346	2347	2348	2349	2350	2351	2352	2353	2354	2355	2356	2357	2358	2359	2360	2361	2362	2363	2364	2365	2366	2367	2368	2369	2370	2371	2372	2373	2374	2375	2376	2377	2378	2379	2380	2381	2382	2383	2384	2385	2386	2387	2388	2389	2390	2391	2392	2393	2394	2395	2396	2397	2398	2399	2400	2401	2402	2403	2404	2405	2406	2407	2408	2409	2410	2411	2412	2413	2414	2415	2416	2417	2418	2419	2420	2421	2422	2
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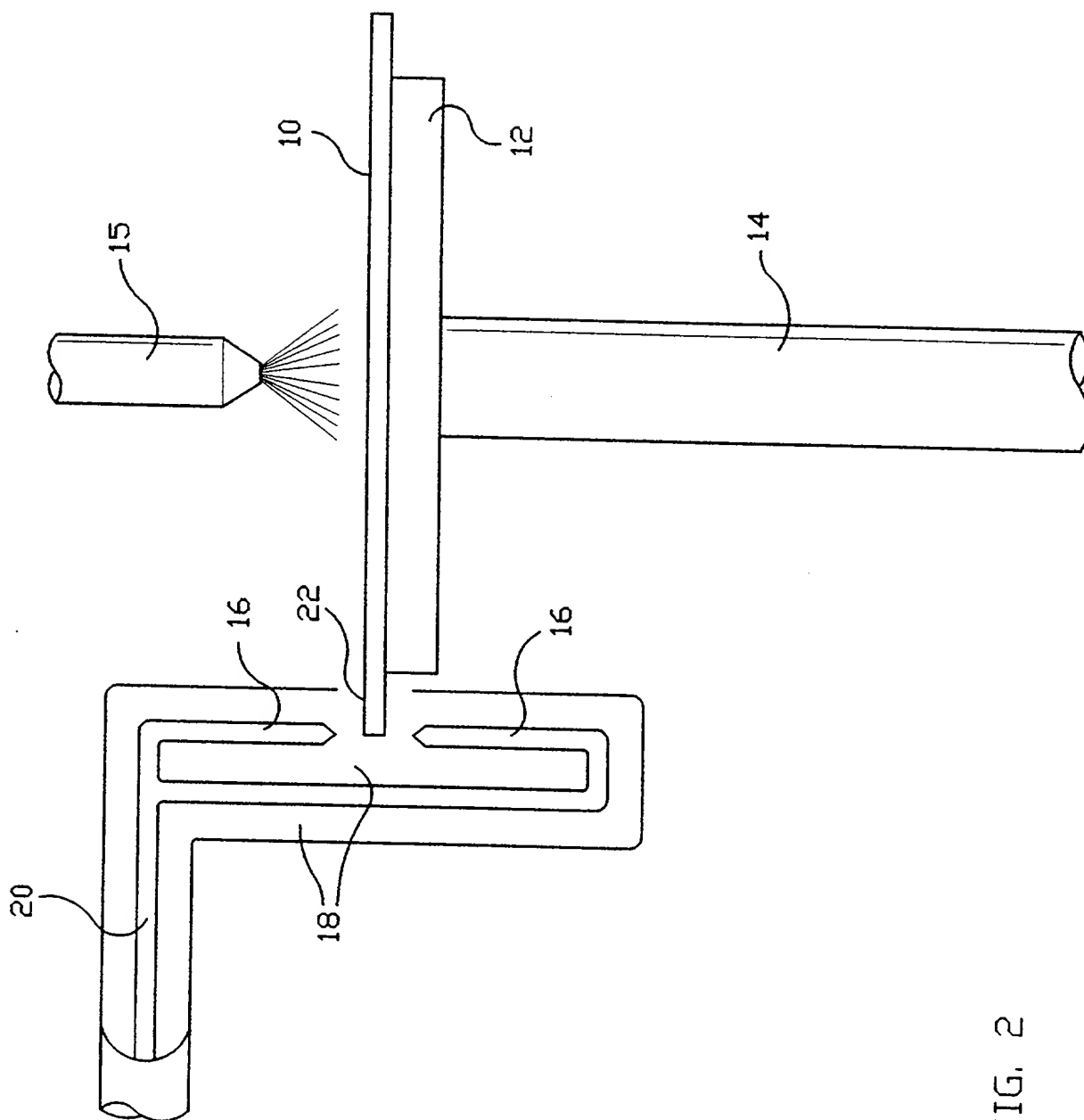


FIG. 2

DECLARATION AND POWER OF ATTORNEY

As below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled; CHEMICAL DISPENSING SYSTEM FOR SEMICONDUCTOR WAFER PROCESSING, specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations Section 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: NONE.

I hereby claim the benefit under Title 35, United States Code Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: NONE.

I hereby declare that all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As the named inventor, I appoint the following as attorneys to transact all business in the Patent and Trademark Office for this application -- Steven R. Ormiston (Registration No. 35,974), Margaret M. Dunbar (Registration No. 37,818); Craig M. Korfanta (Registration No. 33,255) Bryan Farney (Registration No. 32,651), and Lia M. Pappas (Registration No. 34,095).

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Inventor's Full Name: Trung T. Doan

Inventor's Signature:  Date: 2/20/96

Citizenship: United States of America

Post Office Address: 1574 Shenandoah Drive

City, State and
Country of Residence: Boise, Idaho, 83712 United States of America

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Trung T. Doan

Serial No.: Unknown

Filed: 8/14/98

For: CHEMICAL DISPENSING SYSTEM FOR
SEMICONDUCTOR WAFER PROCESSING

§ Atty. Docket: 93-0421.03
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I HEREBY CERTIFY THAT THIS PAPER IS BEING DEPOSITED
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Signature

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF ATTORNEY

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment recorded in the United States Patent and Trademark Office as set forth below or filed herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventor(s).

The Assignee hereby revokes any previous Powers of Attorney and appoints: Charles B. Brantley, II, Reg. No. 38,086; Michael L. Lynch, Reg. No. 30,871; Lia M. Pappas, Reg. No. 34,095; W. Eric Webostad, Reg. No. 35,406; Walter D. Fields, Reg. No. 37,130; Susan B. Collier, Reg. No. 34, 566; Kevin D. Martin, Reg. No. 37,882; and David J. Paul, Reg. No. 34,692 as its attorney or agent, with full power of substitution and revocation, to prosecute the application, to make alterations and amendments therein, to transact all business in the Patent and Trademark Office in connection therewith, to receive any Letters Patent, and for one year after issuance of such Letters Patent to file any request for a certificate of correction that may be deemed appropriate.

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC. referenced below, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

Assignment:

☐ Filed concurrently herewith for recording, a copy of which is attached hereto.

☒ Previously recorded on: 2/27/96,
at Reel: 7995 Frame: 0626.

Please direct all communications as follows:

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MICRON TECHNOLOGY, INC.
8000 S. Federal Way
Boise, ID 83706-9632
(208) 368-4557

ASSIGNEE: MICRON TECHNOLOGY, INC.

Date: Aug 14, 1998

By: [Signature]
Michael L. Lynch, Reg. No. 30,871
Chief Patent Counsel